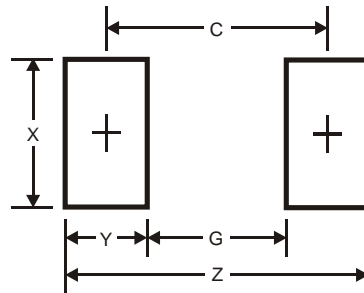
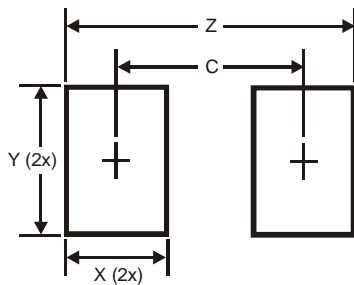


X1-DFN1006-2 / X2-DFN1006-2 / MiniMELF / MELF / SOD323 / SOD123 / SOD523 / SMA / SMB / SMC



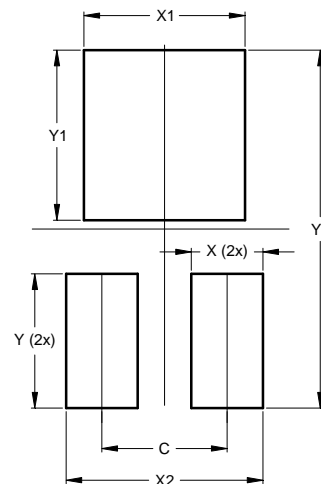
Dimensions	X1-DFN1006-2 / X2-DFN1006-2	MiniMELF	MELF	SOD123	SOD323	SOD523	SMA	SMB	SMC
Z	1.1	4.7	6.3	4.9	3.75	2.3	6.5	6.8	9.4
G	0.3	2.1	3.3	2.5	1.05	1.1	1.5	1.8	4.4
X	0.7	1.7	2.7	0.7	0.65	0.8	1.7	2.3	3.3
Y	0.4	1.3	1.5	1.2	1.35	0.6	2.5	2.5	2.5
C	0.7	3.5	4.8	3.7	2.40	1.7	4.0	4.3	6.8

X3-DFN0603-2



Dimensions	Value (in mm)
C	0.355
X	0.230
Y	0.300
Z	0.610

X2-DFN0806-3

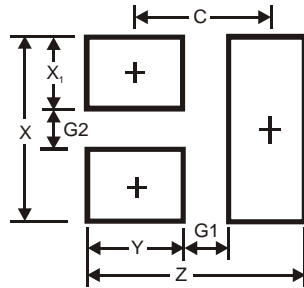


Dimensions	Value (in mm)
C	0.350
X	0.200
X1	0.450
X2	0.550
Y	0.375
Y1	0.475
Y2	1.000

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

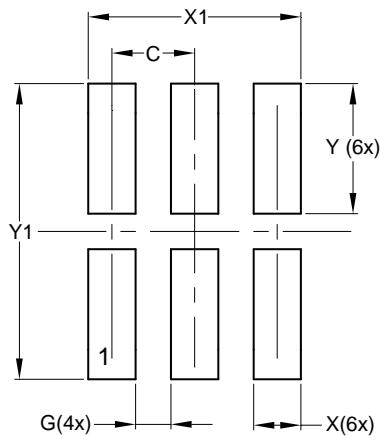
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**X1-DFN1006-3 / X2-DFN1006-3**



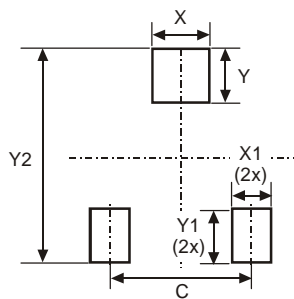
Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

**X2-DFN1010-6**



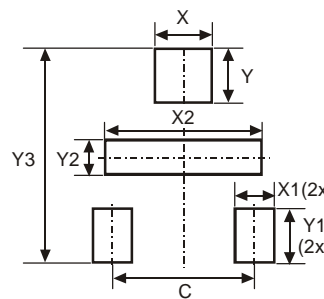
Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

**X1-DFN1212-3**



Dimensions	Value (in mm)
C	0.80
X	0.42
X1	0.32
Y	0.50
Y1	0.50
Y2	1.50

**X1-DFN1212-3  
Type B**

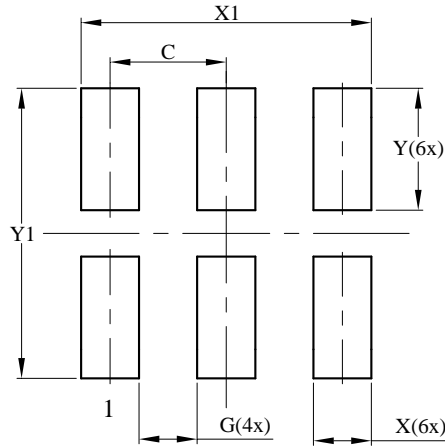


Dimensions	Value (in mm)
C	0.80
X	0.42
X1	0.32
X2	0.90
Y	0.50
Y1	0.50
Y2	0.20
Y3	1.50

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

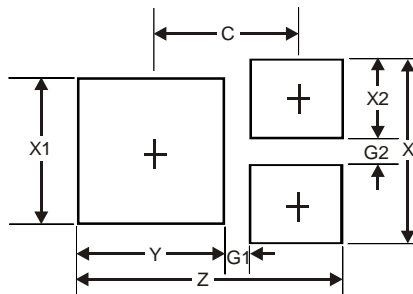
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**X2-DFN1410-6**



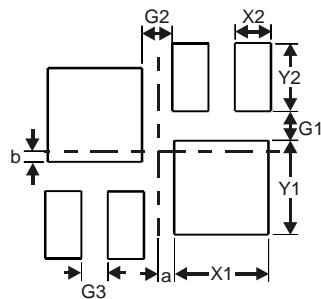
Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

**X1-DFN1411-3**



Dimensions	Value (in mm)
Z	1.38
G1	0.15
G2	0.15
X	0.95
X1	0.75
X2	0.40
Y	0.75
C	0.76

**X1-DFN1612-6 / X2-DFN1310-6**

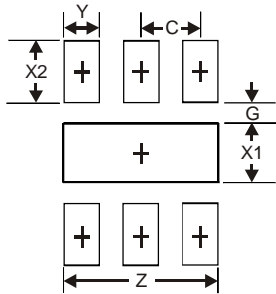


Dimensions	X1-DFN1612-6	X2-DFN1310-6
G1	0.15	0.16
G2	0.175	0.17
G3	0.15	0.15
X1	0.60	0.52
X2	0.25	0.20
Y1	0.65	0.52
Y2	0.45	0.375
a	0.10	0.09
b	0.15	0.06

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

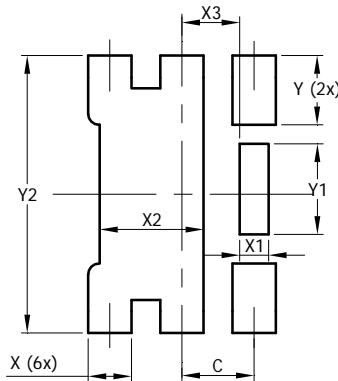
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**U-DFN1616-6**



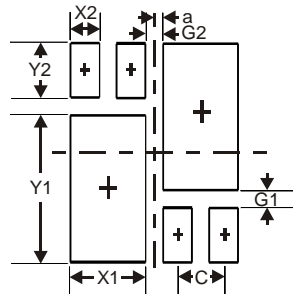
Dimensions	Value (in mm)
Z	1.3
G	0.175
X1	0.50
X2	0.525
Y	0.30
C	0.50

**X1-DFN1616-6 Type E**



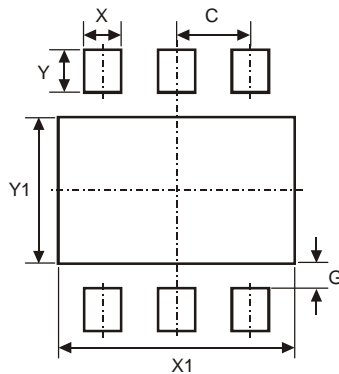
Dimensions	Value (in mm)
C	0.500
X	0.300
X1	0.200
X2	0.720
X3	0.400
Y	0.475
Y1	0.620
Y2	1.900

**U-DFN1616-8**



Dimensions	Value (in mm)
G1	0.15
G2	0.20
X1	0.65
X2	0.25
Y1	1.25
Y2	0.50
C	0.40
a	0.10

**U-DFN2018-6**

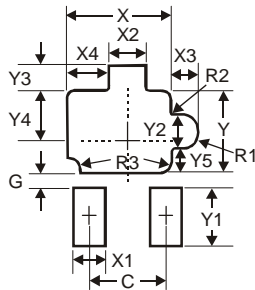


Dimensions	Value (in mm)
C	0.50
G	0.20
X	0.25
X1	1.60
Y	0.35
Y1	1.20

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

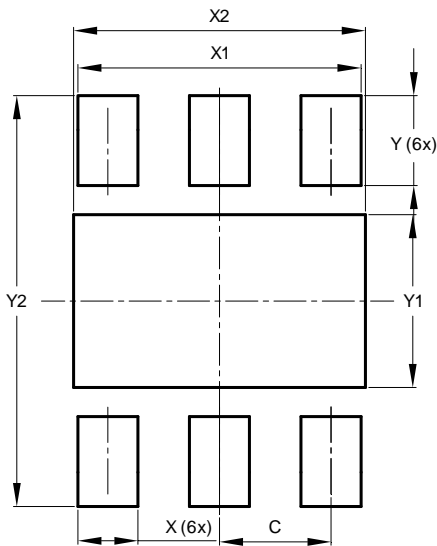
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**U-DFN2020-3**



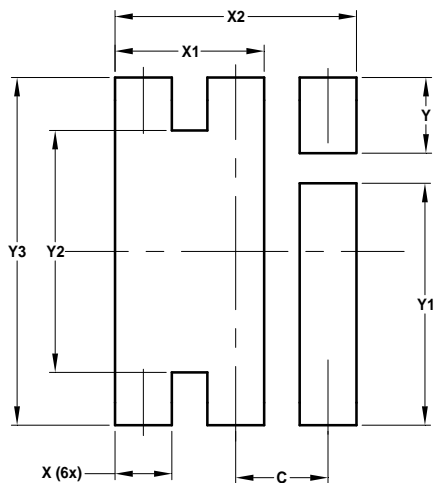
Dimensions	Value (in mm)	Dimensions	Value (in mm)
C	1.00	Y1	0.60
G	0.15	Y2	0.45
X	1.40	Y3	0.45
X1	0.35	Y4	0.698
X2	0.45	Y5	0.313
X3	0.322	R1	0.225
X4	0.60	R2	0.05
Y	1.10	R3	0.20

**U-DFN2020-6**



Dimensions	Value (in mm)
C	0.650
X	0.350
X1	1.650
X2	1.700
Y	0.525
Y1	1.010
Y2	2.400

**X2-DFN2020-6**

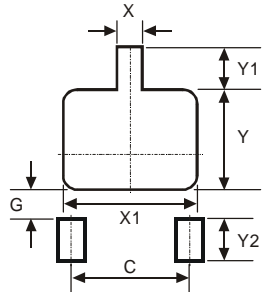


Dimensions	Value (in mm)
C	0.650
X	0.400
X1	1.050
X2	1.700
Y	0.500
Y1	1.600
Y2	1.600
Y3	2.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

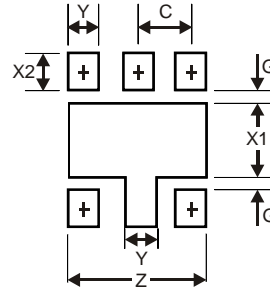
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**U-DFN2020-3  
Type B**



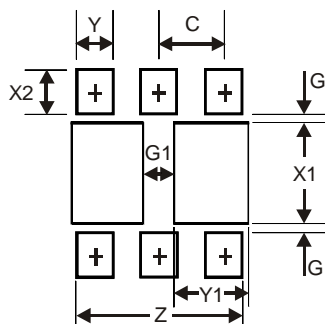
Dimensions	Value (in mm)
C	1.30
G	0.24
X	0.35
X1	1.52
Y	1.09
Y1	0.47
Y2	0.50

**U-DFN2020-6**



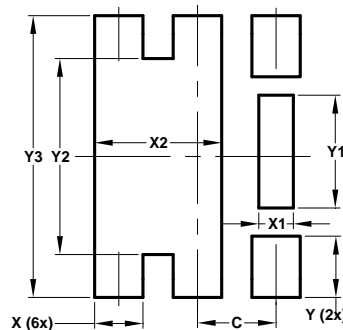
Dimensions	Value (in mm)
Z	1.67
G	0.15
X1	0.90
X2	0.45
Y	0.37
C	0.65

**U-DFN2020-6  
Type B**



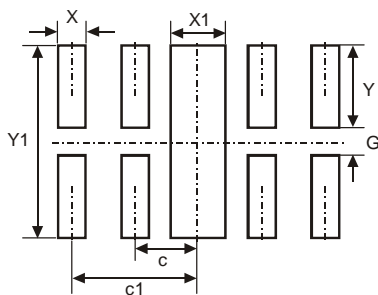
Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

**U-DFN2020-6  
Type E**



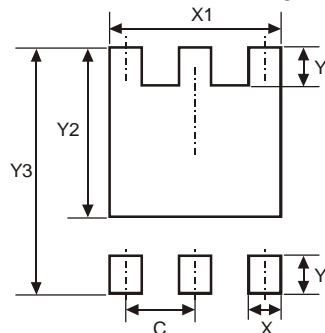
Dimensions	Value (in mm)
C	0.650
X	0.400
X1	0.285
X2	1.050
Y	0.500
Y1	0.920
Y2	1.600
Y3	2.300

**U-DFN2510-8**



Dimensions	Value (in mm)
c	0.5
c1	1.0
G	0.2
X	0.2
X1	0.4
Y	0.6
Y1	1.4

**U-DFN2523-6**

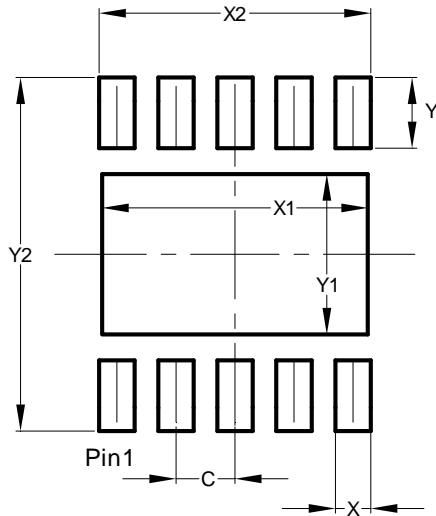


Dimensions	Value (in mm)
C	0.650
X	0.400
X1	1.700
Y	0.650
Y1	0.450
Y2	1.830
Y3	2.700

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

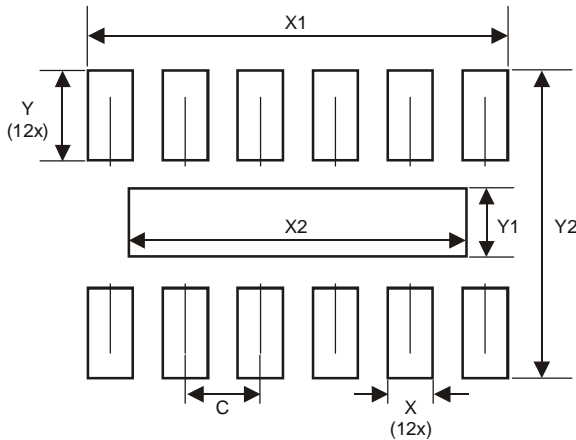
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**U-DFN2626-10**



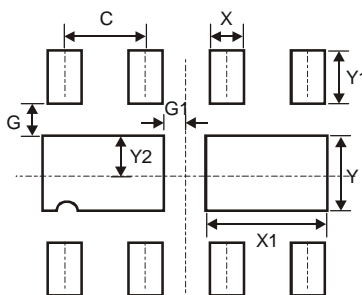
Dimensions	Value (in mm)
C	0.500
X	0.300
X1	2.250
X2	2.300
Y	0.600
Y1	1.360
Y2	3.000

**U-DFN3016-12**



Dimensions	Value (in mm)
C	0.500
X	0.300
X1	2.800
X2	2.250
Y	0.600
Y1	0.450
Y2	2.050

**W-DFN3020-8  
Type B**

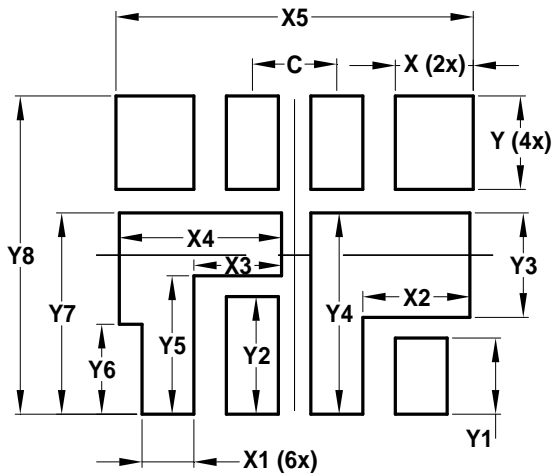


Dimensions	Value (in mm)
C	0.650
G	0.285
G1	0.090
X	0.400
X1	1.120
Y	0.730
Y1	0.500
Y2	0.365

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

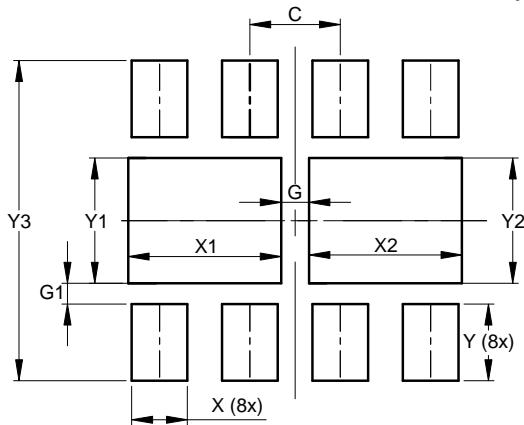
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**W-DFN3020-8**  
Type K



Dimensions	Value (in mm)
C	0.650
X	0.600
X1	0.400
X2	0.825
X3	0.675
X4	1.250
X5	2.750
Y	0.675
Y1	0.550
Y2	0.850
Y3	0.755
Y4	1.455
Y5	1.000
Y6	0.650
Y7	1.455
Y8	2.300

**U-DFN3020-8**  
Type E



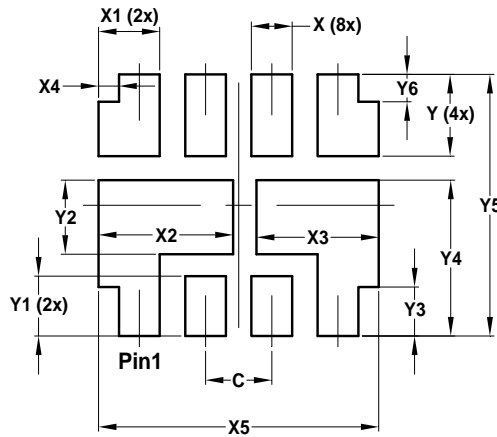
Dimensions	Value (in mm)
C	0.650
G	0.200
G1	0.150
X	0.400
X1	1.100
X2	1.100
Y	0.550
Y1	0.900
Y2	0.900
Y3	2.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

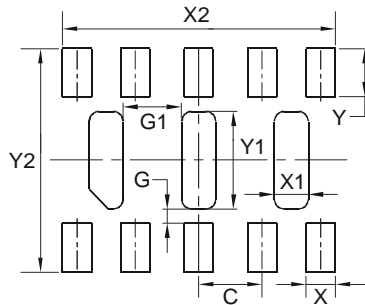


**U-DFN3020-8**  
Type M



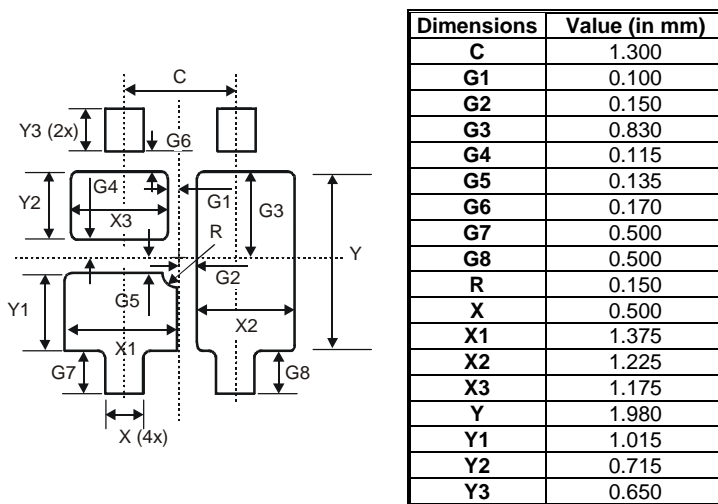
Dimensions	Value (in mm)
C	0.650
X	0.400
X1	0.600
X2	1.320
X3	1.200
X4	0.200
X5	2.750
Y	0.750
Y1	0.550
Y2	0.680
Y3	0.450
Y4	0.430
Y5	2.400
Y6	0.250

**U-DFN3020-10**



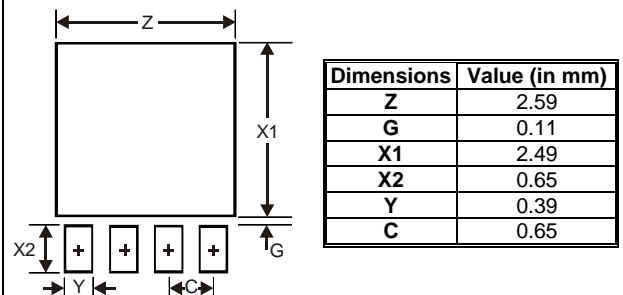
Dimensions	Value (in mm)
C	0.650
G	0.150
G1	0.600
X	0.300
X1	0.350
X2	2.800
Y	0.500
Y1	1.000
Y2	2.300

**U-DFN3030-4**



Dimensions	Value (in mm)
C	1.300
G1	0.100
G2	0.150
G3	0.830
G4	0.115
G5	0.135
G6	0.170
G7	0.500
G8	0.500
R	0.150
X	0.500
X1	1.375
X2	1.225
X3	1.175
Y	1.980
Y1	1.015
Y2	0.715
Y3	0.650

**U-DFN3030-8**



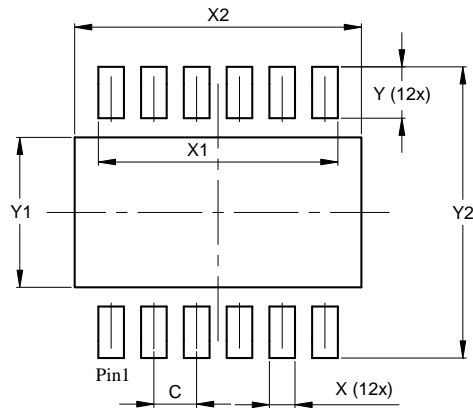
Dimensions	Value (in mm)
Z	2.59
G	0.11
X1	2.49
X2	0.65
Y	0.39
C	0.65

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

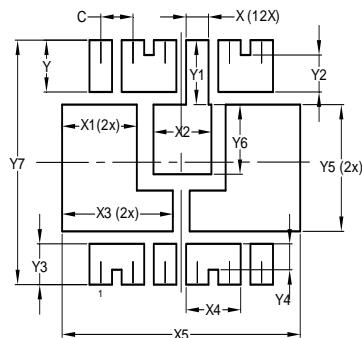


**U-DFN4030-12**



Dimensions	Value (in mm)
C	0.500
X	0.300
X1	2.800
X2	3.350
Y	0.600
Y1	1.750
Y2	3.400

**U-DFN4030-12 Type B**

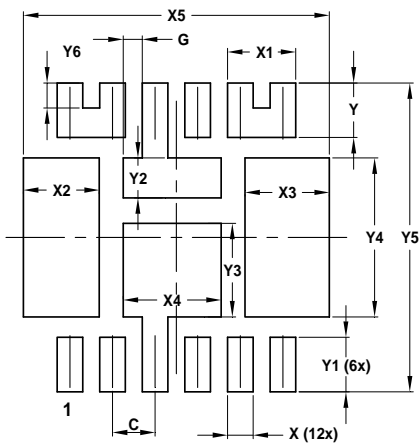


Dimensions	Value (in mm)
C	0.500
X	0.350
X1	1.160
X2	0.900
X3	1.720
X4	0.850
X5	3.700
Y	0.700
Y1	0.870
Y2	0.500
Y3	0.550
Y4	0.350
Y5	1.710
Y6	0.940
Y7	3.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

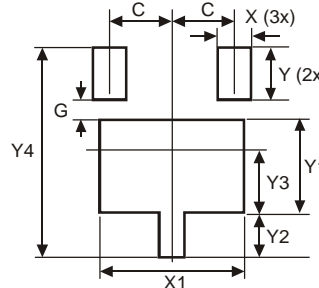
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**U-DFN4030-12 Type C**



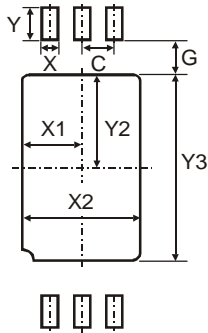
Dimensions	Value (in mm)
C	0.500
G	0.225
X	0.300
X1	0.800
X2	0.890
X3	0.990
X4	1.150
X5	3.590
Y	0.600
Y1	0.600
Y2	0.440
Y3	1.030
Y4	1.750
Y5	3.400
Y6	0.275

**DFN322**



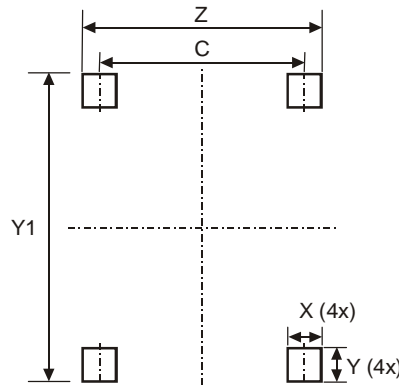
Dimensions	Value (in mm)
C	0.65
G	0.20
X	0.35
X1	1.52
Y	0.55
Y1	0.98
Y2	0.47
Y3	0.63
Y4	2.20

**W-DFN5020-6**



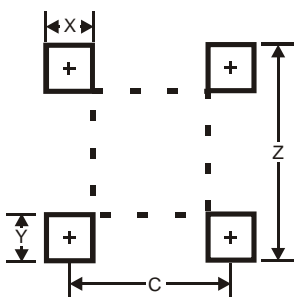
Dimensions	Value (in mm)
C	0.50
G	0.35
X	0.35
X1	0.90
X2	1.80
Y	0.70
Y2	1.60
Y3	3.20

**W-DFN5060-4**



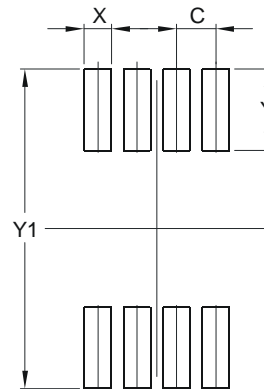
Dimensions	Value (in mm)
C	4.00
X	0.75
Y	0.95
Y1	6.20
Z	4.75

**DF-S / MiniDIP**



Dimensions	DF-S	MiniDIP
Z	10.26	6.91
X	1.2	0.60
Y	1.52	0.76
C	5.2	2.67

**MSOP-8**

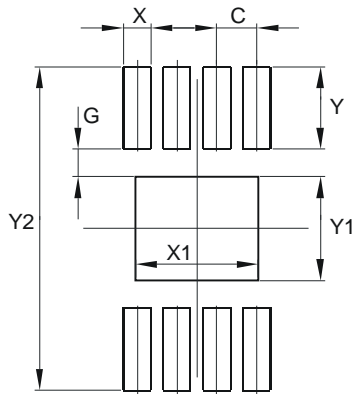


Dimensions	Value (in mm)
C	0.650
X	0.450
Y	1.350
Y1	5.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

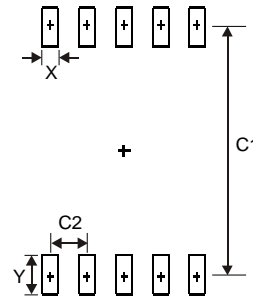
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**MSOP8-EP**



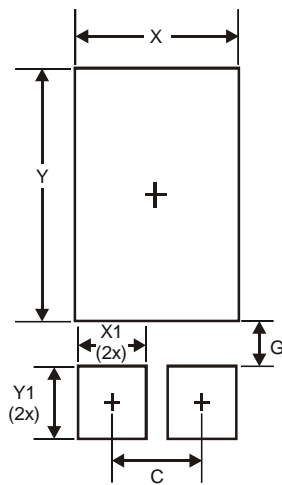
Dimensions	Value (in mm)
C	0.650
G	0.450
X	0.450
X1	2.000
Y	1.350
Y1	1.700
Y2	5.300

**MSOP-10**



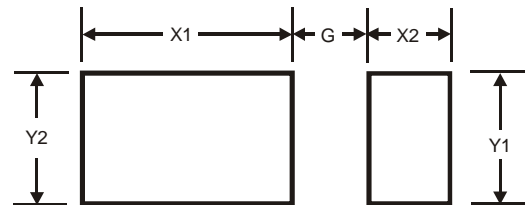
Dimensions	Value (in mm)
X	0.30
Y	1.4
C1	4.4
C2	0.50

**POWERDI®5**



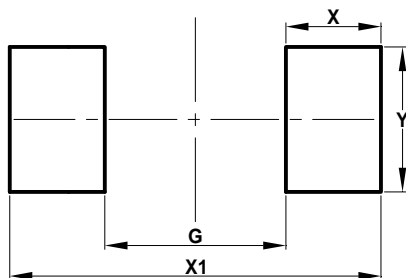
Dimensions	Value (in mm)
C	1.840
G	0.852
X	3.360
X1	1.390
Y	4.860
Y1	1.400

**POWERDI®123 / POWERDI®323**



Dimensions	POWERDI®123	POWERDI®323
G	1.0	0.5
X1	2.2	2.0
X2	0.9	0.8
Y1	1.4	0.8
Y2	1.4	1.1

**POWERDI®123 Type B**

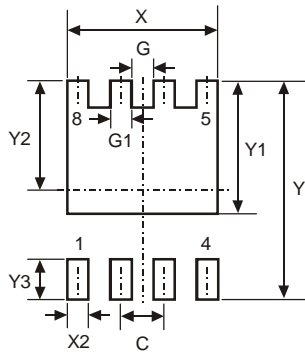


Dimensions	Value (in mm)
G	2.000
X	1.050
X1	4.100
Y	1.500

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

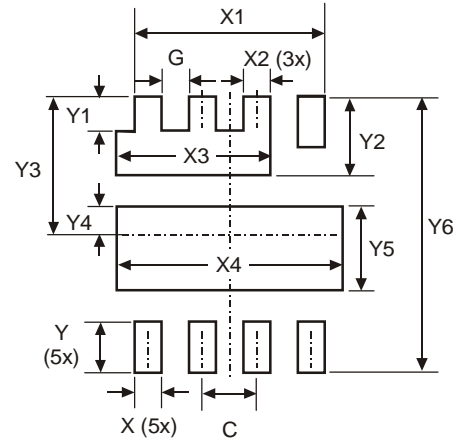
**POWERDI®3333-8**



Dimensions	Value (in mm)
C	0.650
G	0.230
G1	0.420
Y	3.700
Y1	2.250
Y2	1.850
Y3	0.700
X	2.370
X2	0.420

**POWERDI®3333-8**

**Type B**

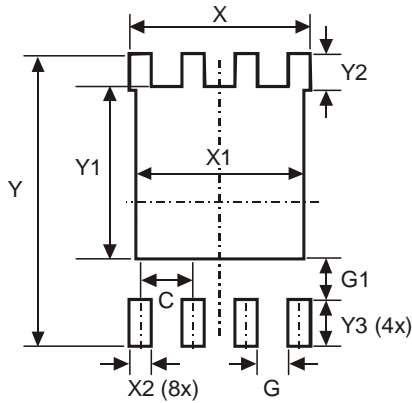


Dimensions	Value (in mm)
C	0.650
G	0.230
X	0.420
X1	2.370
X2	0.420
X3	1.890
X4	2.710
Y	0.700
Y1	0.400
Y2	1.160
Y3	1.850
Y4	0.405
Y5	1.295
Y6	3.700

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

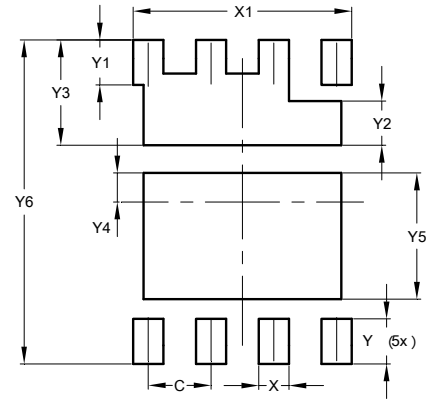
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**POWERDI®5060-8**



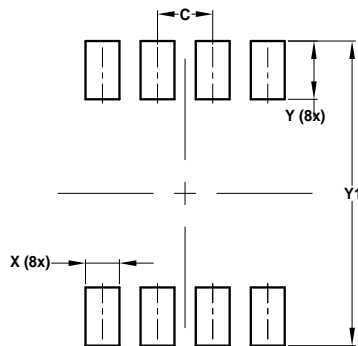
Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	4.420
X1	4.100
X2	0.610
Y	6.610
Y1	3.810
Y2	1.020
Y3	1.270

**POWERDI®5060-8  
Type B**



Dimensions	Value (in mm)
C	1.270
X	0.610
X1	4.420
Y	0.910
Y1	0.910
Y2	0.895
Y3	2.130
Y4	0.585
Y5	2.550
Y6	6.550

**POWERDI®3030-8**

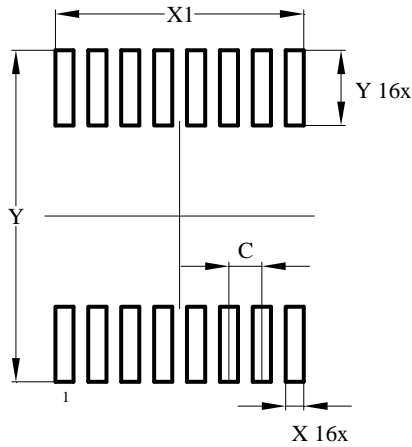


Dimensions	Value (in mm)
C	0.650
X	0.400
Y	0.850
Y1	3.400

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

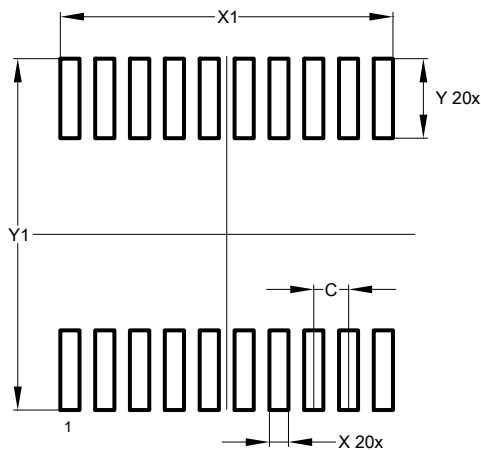
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**QSOP-16**



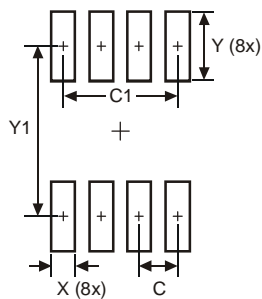
Dimensions	Value (in mm)
C	0.635
X	0.350
X1	4.795
Y	1.450
Y1	6.400

**QSOP-20**



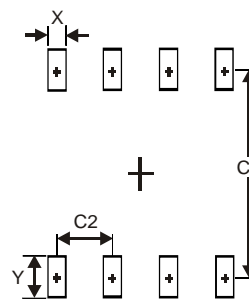
Dimensions	Value (in mm)
C	0.635
X	0.350
X1	6.065
Y	1.450
Y1	6.400

**SM-8**



Dimensions	Value (in mm)
C	1.52
C1	4.6
X	0.95
Y	2.80
Y1	6.80

**SO-8**



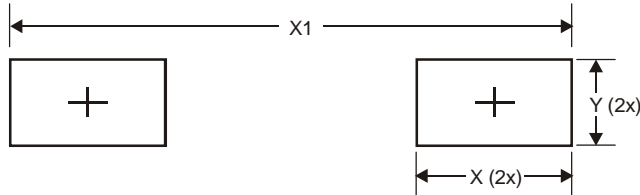
Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

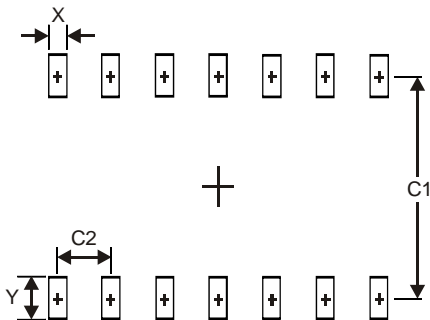


**SOD323F**



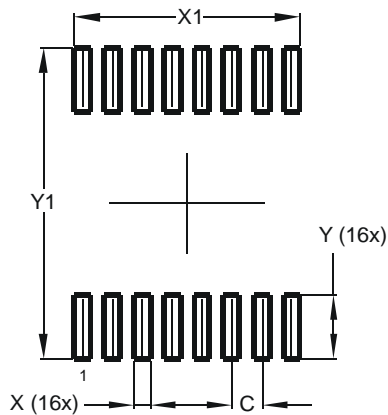
Dimensions	Value (in mm)
X	0.710
X1	2.700
Y	0.403

**SOP-14**



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

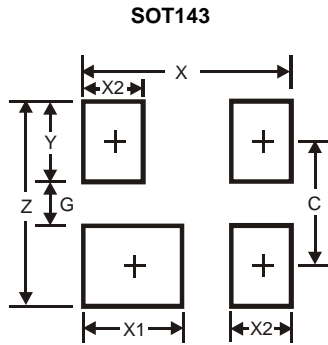
**SOP-16**



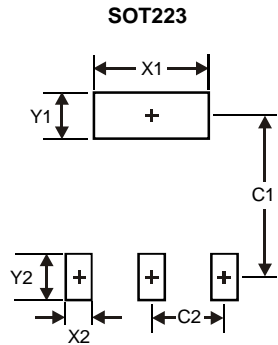
Dimensions	Value (in mm)
C	1.270
X	0.670
X1	9.560
Y	1.450
Y1	6.400

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

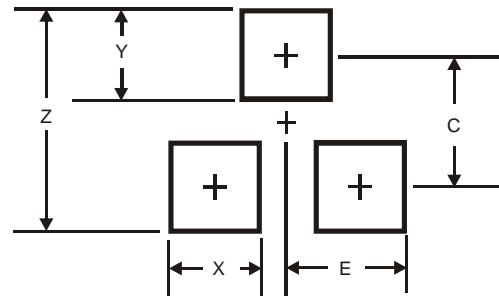


Dimensions	Value (in mm)
Z	2.70
G	1.30
X	2.50
X1	1.0
X2	0.60
Y	0.70
C	2.0



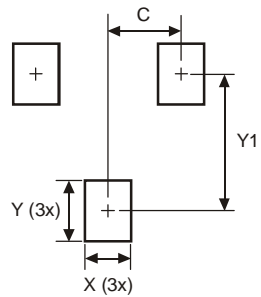
Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3

**SOT523 / SOT323 / SOT23 / SC59**



Dimensions	SOT523	SOT323	SOT23	SC59
Z	1.8	2.8	2.9	3.4
X	0.4	0.7	0.8	0.8
Y	0.51	0.9	0.9	1.0
C	1.3	1.9	2.0	2.4
E	0.7	1.0	1.35	1.35

**SOT23F**

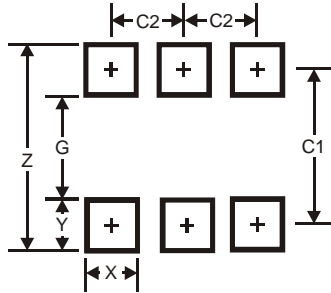


Dimensions	Value (in mm)
C	0.95
X	0.60
Y	0.80
Y1	1.80

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

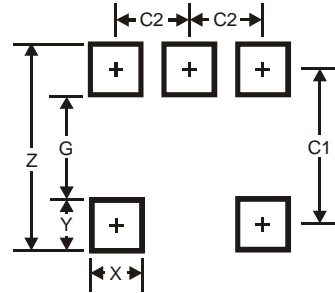
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**SC74R / SOT26 / SOT363 / SOT563**



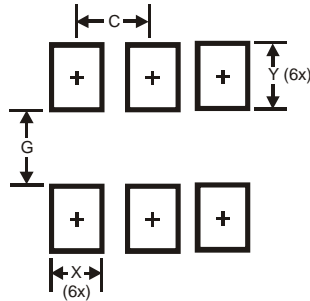
Dimensions	SC74R / SOT26	SOT363	SOT563
Z	3.20	2.5	2.2
G	1.60	1.3	1.2
X	0.55	0.42	0.375
Y	0.80	0.6	0.5
C1	2.40	1.9	1.7
C2	0.95	0.65	0.5

**SOT25 / SOT353 / SOT553**



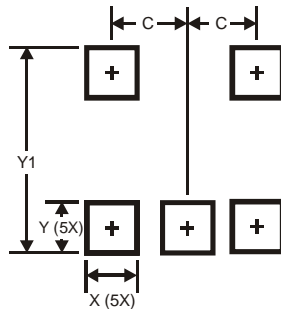
Dimensions	SOT25	SOT353	SOT553
Z	3.20	2.5	2.2
G	1.60	1.3	1.2
X	0.55	0.42	0.375
Y	0.80	0.6	0.5
C1	2.40	1.9	1.7
C2	0.95	0.65	0.5

**SOT666**



Dimensions	Value (in mm)
C	0.50
G	0.80
X	0.35
Y	0.50

**SOT953**

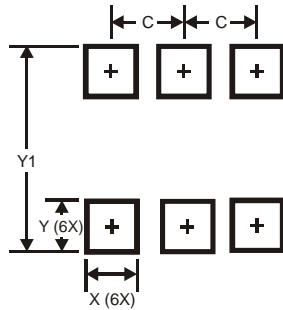


Dimensions	Value (in mm)
C	0.350
X	0.200
Y	0.200
Y1	1.100

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

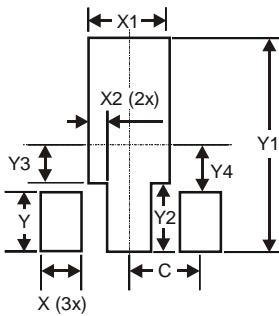
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**SOT963**



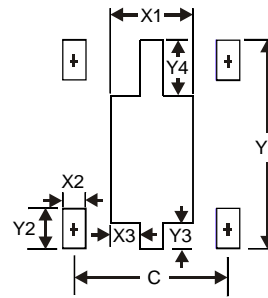
Dimensions	Value (in mm)
C	0.350
X	0.200
Y	0.200
Y1	1.100

**SOT89-3**



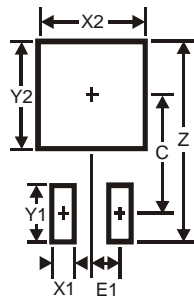
Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

**SOT89-5**



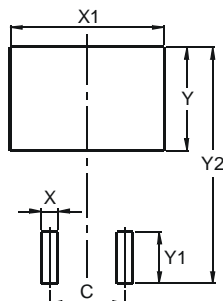
Dimensions	Value (in mm)
X1	1.7
X2	0.55
X3	0.4
Y1	4.6
Y2	1.2
Y3	0.5
Y4	1.1
C	3.0

**TO252 (DPAK)**



Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
C	6.9
E1	2.3

**TO263 (D<sup>2</sup>PAK)**

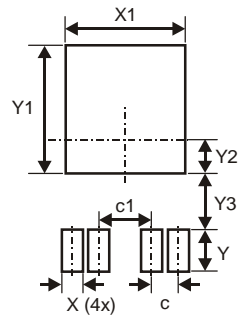


Dimensions	Value (in mm)
C	5.08
X	1.10
X1	10.41
Y	3.50
Y1	7.01
Y2	15.99

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

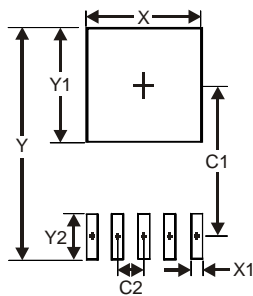
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**TO252-4**



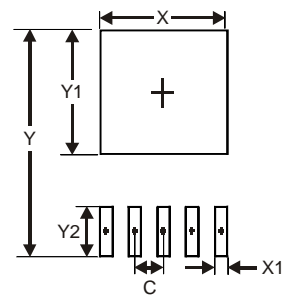
Dimensions	Value (in mm)
c	1.27
c1	2.54
X	1.00
X1	5.73
Y	2.00
Y1	6.17
Y2	1.64
Y3	2.66

**TO252-5**



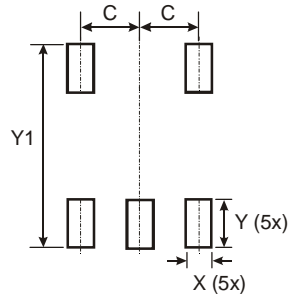
Dimensions	Value (in mm)
X	5.6
X1	0.6
Y	11.0
Y1	5.6
Y2	2.0
C1	7.2
C2	1.27

**TO263-5**



Dimensions	Value (in mm)
X	10.9
X1	1.05
Y	15.7
Y1	9.1
Y2	2.5
C	1.7

**TSOT25**

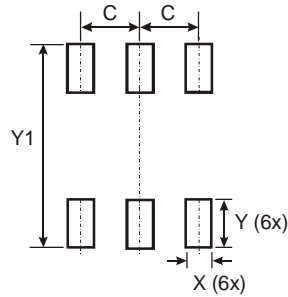


Dimensions	Value (in mm)
C	0.950
X	0.700
Y	1.000
Y1	3.199

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

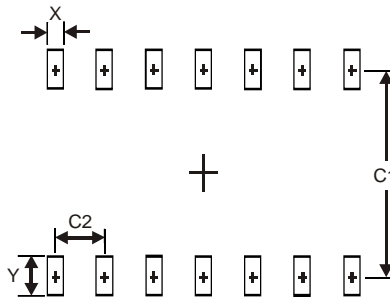
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**TSOT26**



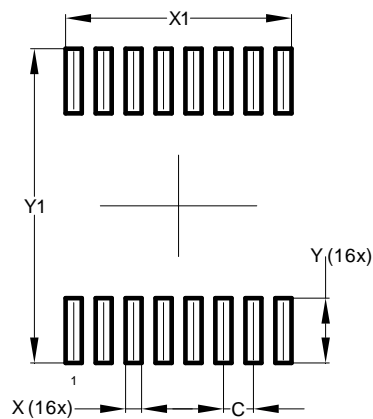
Dimensions	Value (in mm)
C	0.950
X	0.700
Y	1.000
Y1	3.199

**TSSOP-14**



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

**TSSOP-16**

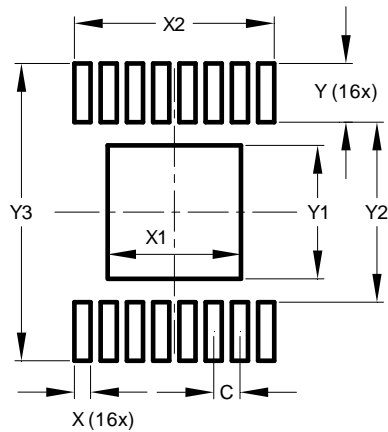


Dimensions	Value (in mm)
C	0.650
X	0.350
X1	4.900
Y	1.400
Y1	6.800

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

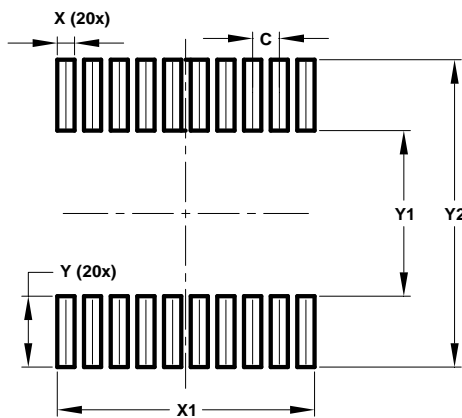
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**TSSOP-16EP**



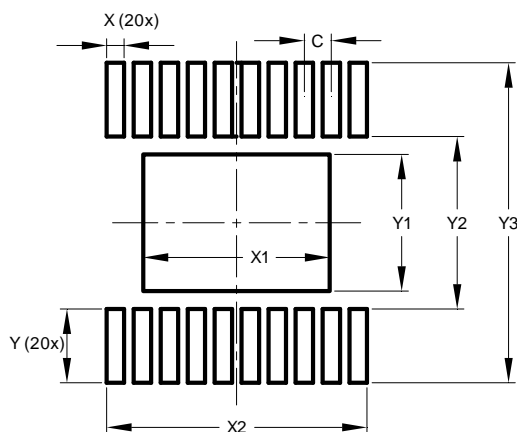
Dimensions	Value (in mm)
C	0.650
X	0.450
X1	3.290
X2	5.000
Y	1.450
Y1	3.290
Y2	4.450
Y3	7.350

**TSSOP-20**



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	6.270
Y	1.780
Y1	4.160
Y2	7.720

**TSSOP-20EP**

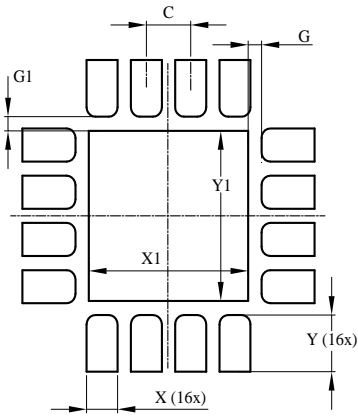


Dimensions	Value (in mm)
C	0.650
X	0.420
X1	4.490
X2	6.270
Y	1.780
Y1	3.290
Y2	4.160
Y3	7.720

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

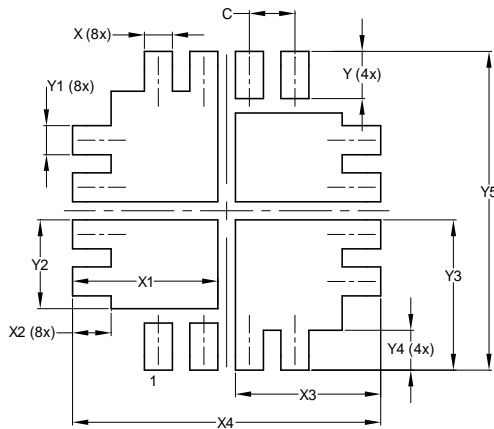
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**U-QFN3030-16 Type B**



Dimensions	Value (in mm)
C	0.500
G	0.150
G1	0.150
X	0.350
X1	1.800
Y	0.600
Y1	1.800

**U-QFN4040-16 Type C**



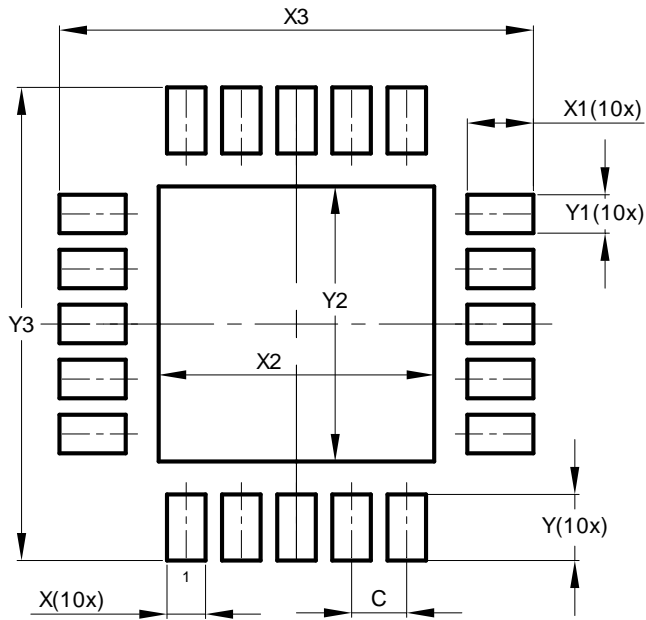
Dimensions	Value (in mm)
C	0.650
X	0.400
X1	2.075
X2	0.550
X3	2.075
X4	4.400
Y	0.650
Y1	0.400
Y2	1.225
Y3	2.075
Y4	0.550
Y5	4.400

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

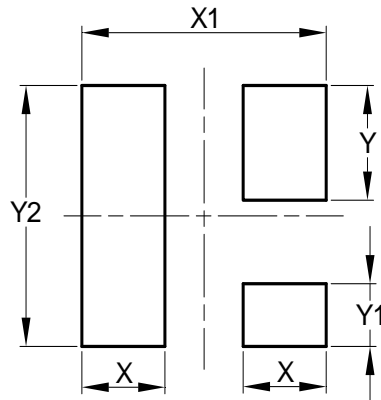


**U-QFN4040-20**



Dimensions	Value (in mm)
C	0.500
X	0.350
X1	0.600
X2	2.500
X3	4.300
Y	0.600
Y1	0.350
Y2	2.500
Y3	4.300

**X2-WLB0505-3**

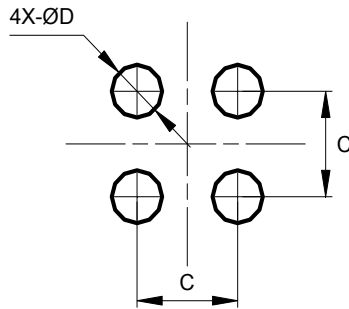


Dimensions	Value (in mm)
X	0.17
X1	0.50
Y	0.22
Y1	0.12
Y2	0.50

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

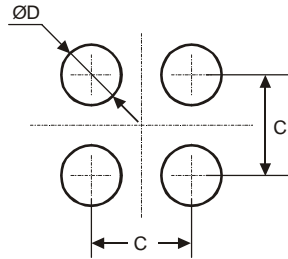
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**X2-WLB0808-4**



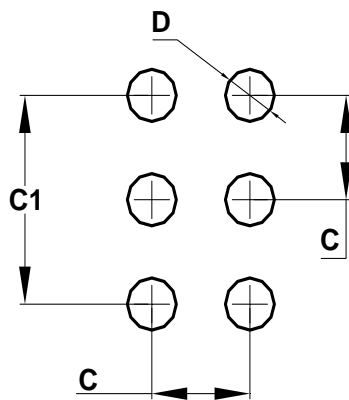
Dimensions	Value (in mm)
C	0.40
D	0.20

**U-WLB1010-4**



Dimensions	Value (in mm)
C	0.50
D	0.25

**U-WLB1510-6**

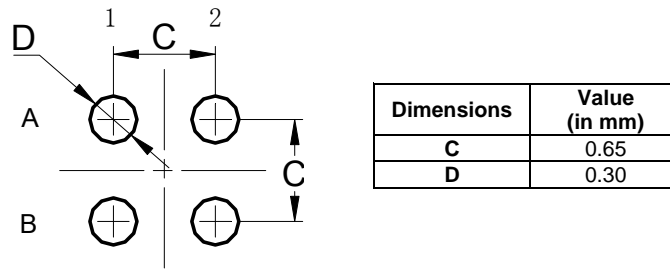


Dimensions	Value (in mm)
C	0.50
C1	1.00
D	0.25

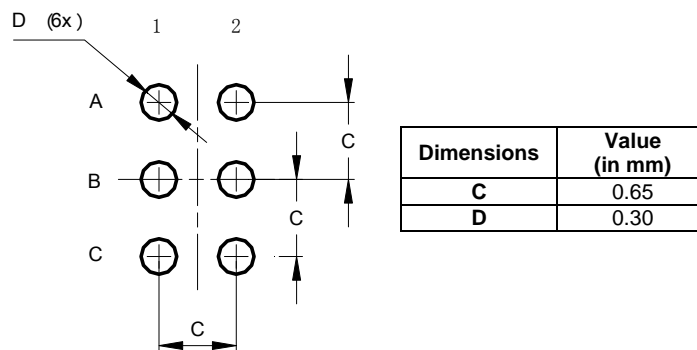
**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

**X2-WLB1818-4**



**X2-WLB2718-6**



**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.